



EXPEDITED PROCEDURE – EXAMINING GROUP 2814

09/733,289

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Xiao-Chun Mu et al.	Examiner:	DiLinh Nguyen
Serial No.:	09/733,289	Group Art Unit:	2814
Filed:	December 8, 2000	Docket No.:	884.798US1
Title:	Microelectronic Package Having an Integrated Heat Sink and Build-Up Layers		
Assignee:	Intel Corporation	Customer Number:	21186

RESPONSE UNDER 37 C.F.R. 1.116

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In response to the Final Office Action mailed October 5, 2005, please consider the remarks as follows: